PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chia-Jen CHEN	04/18/2005
Hsin-Chang LEE	04/18/2005
Sheng-Chi CHIN	04/18/2005
Hung Chang HSIEH	04/18/2005
Burn Jeng LIN	04/19/2005

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park Hsin-Chu
City:	Taiwan
State/Country:	CHINA
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11115433

CH $40.00 11115433

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	David M. O'Dell

Total Attachments: 3
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Docket No.: 2003-1424 / 24061.204
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Chia-Jen Chen of Hsin-Chu, Taiwan, R.O.C.

(2) Hsin-Chang Lee of Hsin-Chu, Taiwan, R.O.C.

(3) Sheng-Chi Chin of Hsin-Chu, Taiwan, R.O.C.

(4) Hung Chang Hsieh of Hsin-Chu, Taiwan, R.O.C.

(5) Burn Jeng Lin of Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

System and Method for Manufacturing a Mask for Semiconductor Processing

for which we have executed an application for Letters Patent of the United States of America,

______ of even date filed herewith; and
__X__ filed on April 27, 2005 and assigned application number 11/115,433; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2003-1424 / 24061.204
Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chia-Jen Chen

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310, Taiwan, R.O.C.

Dated: 2005/4/18

Chia-Jen Chen
Inventor Signature

Inventor Name: Hsin-Chang Lee

Residence Address: 3F., NO.26, Lane 394, Sianjheng 2nd Rd., Jhubei City,
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Dated: 2005/4/18

Hsin-Chang Lee
Inventor Signature

Inventor Name: Sheng-Chi Chin

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Dated: 2005/4/18

Sheng-Chi Chin
Inventor Signature

Docket No.: 2003-1424 / 24061.204
Customer No.: 42717

Inventor Name: Hung Chang Hsieh

Residence Address: 9F, No 72-12, Lane 531, Sec 1, GuangFu, HsinChu City. 300
Taiwan (R.O.C.

Dated: 4/18/05

Inventor Signature

Inventor Name: Burn Jeng Lin

Residence Address: 153 Kuang Fu Rd., Sec. 1, Lane 89
Hsin-Chu, Taiwan, R.O.C.

Dated: 4/19/2005

Inventor Signature

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